Product End-of-Life Disassembly Instructions

Product Category: Other Products
Marketing Name / Model [List multiple models if applicable.]
HP FlexFabric 7900 AC Power Module (air ingress from port side)(JG840A)

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	2
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		8
External electrical cables and cords		10
Gas Discharge Lamps		2
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		2
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	1
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		9
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Screwdriver	M3
Iron	100W

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove all securing screws on chasses, total 20.
2. Remove all securing screws on PWB, total 4.
3. Cut down three cables on AC inlet, and pull the LED lamps out from the panel.
4. Soldering off the heatsinks and other electric components from the PWB.
5. Disassemble the heatsinks by screw driver.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

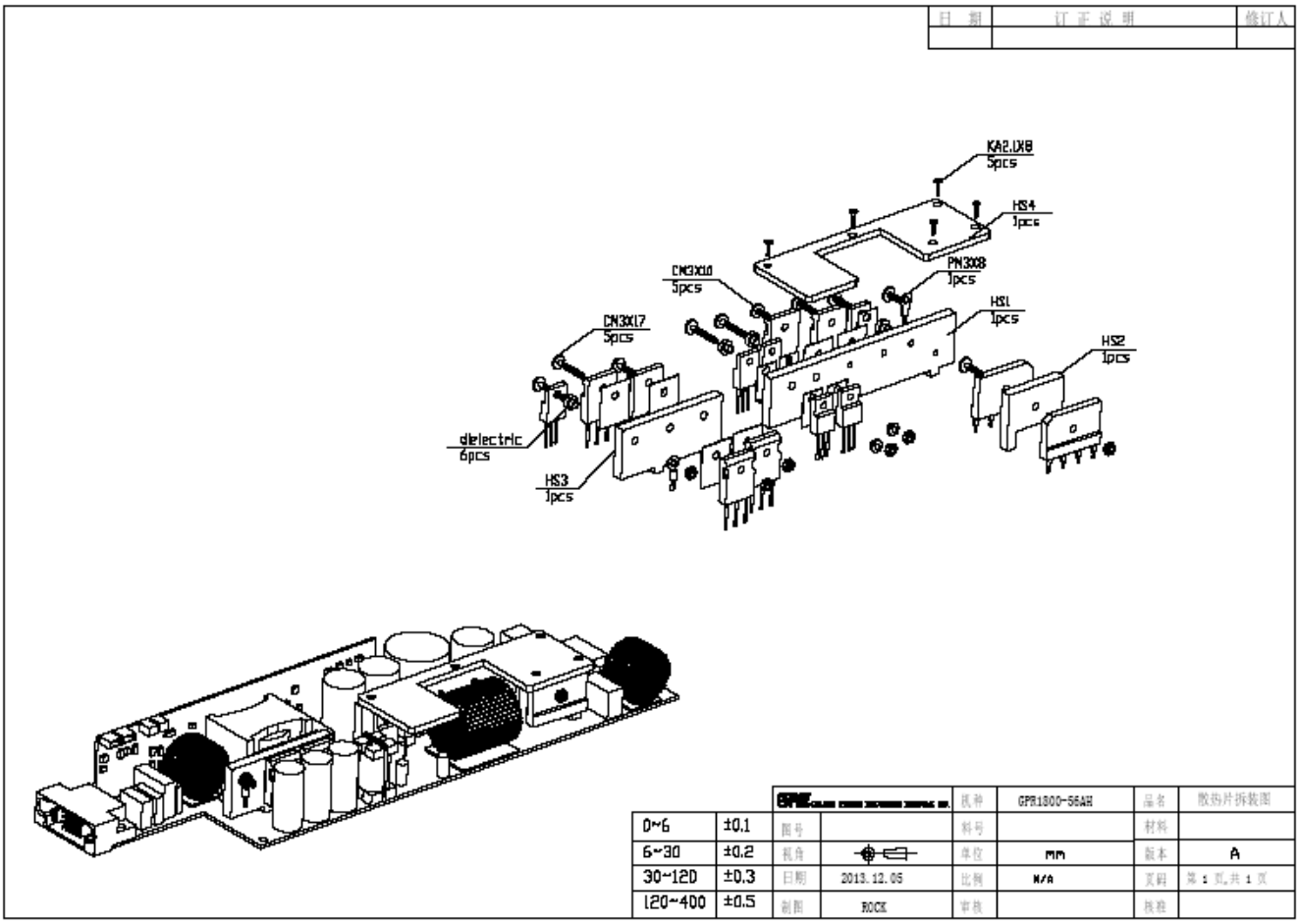

Figure 1 Treatments to the product

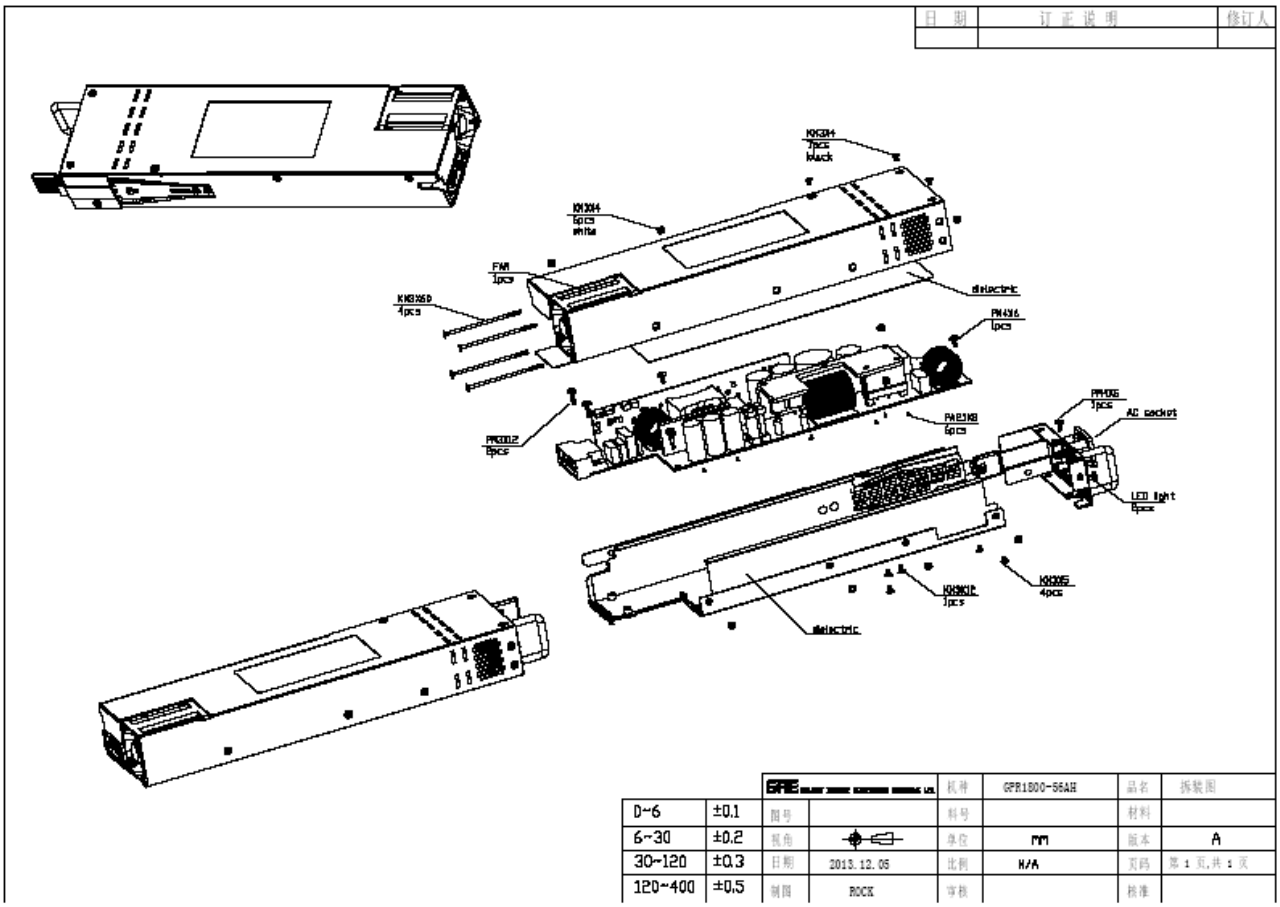

Figure 2 Treatments to the product

3.3 Material of the facility built

Facility	Components	Material	Weight(g)	Weight percentage	Selective treatment for materials and components	Details
AII rsupply	All Components	ROHS	1630.0	100%	All Components	NO
main case	Case Bootom, INLET CORE	Metal part of the lacquer that bake,	352.0	21.59%	Case Bootom, INLET CORE,LED, insulant	Note it with PCB, LED connections
Case TOP	Case TOP，FAN	ROHS	330.5	20.27%	Case TOP	NO
Powersupply	PCB, All electron Components	ROHS	948	58.14%	PCB,HS1,HS2 All electron Components	NO

4. Revised record

Date	Version	Author	Modify content
2013.12.06	V0	Cheng Wei	Initial version